

Film Capacitors

EMI Suppression Capacitors (MKP)

Series/Type: B81123 Date: September 2014

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EMI suppression capacitors (MKP)

Y1 / 250 V AC

B81123

Typical applications

- Y1 class for interference suppression
- "Line to ground" applications
- Double insulation

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Internal series connection
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Self-healing properties
- RoHS-compatible

Terminals

- Parallel wire leads, lead-free tinned
- Standard lead lengths: 6 -1 mm
- Special lead lengths available on request

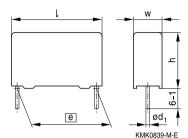
Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), cap. tolerance (code letter), rated AC voltage, series number, sub-class (Y1), dielectric code (MKP), climatic category, passive flammability category, approvals.

Delivery mode

Bulk (untaped) Taped (Ammo pack or reel) For taping details, refer to chapter "Taping and packing".

Dimensional drawing



Dimensions in mm

Lead spacing <u>e</u> ±0.4	Lead diameter d ₁
15, 22.5	0.8

Marking example (position of marks may vary):





KMK1556-L

KMK1557-M



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Approvals

Approval marks Standards		Certificate
EN 60384-14, IEC 60384-14		138584
N UL1414		E97863
CRUIS UL 60384-14, CSA E60384-14		E97863 (approved by UL)

Notes:	Effective January 2014, only for EMI supression capacitors: – UL 60384-14 certification replaces both UL 1414 and UL 1283 standards. – CSA C22.2 No. 1 and CSA C22.s No. 8 are replaced by CSA E60384-14. – References like 1414, 1283 are removed from the capacitor marking
	Capacitors under UL1414, UL1283 produced during or before 2013, are accepted under UL scope.
	Capacitors under CSA C22.2 No.1 / No. 8 produced during or before 2013, are accepted under cUL scope.



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Overview of available types

Lead spacing	15 mm	22.5 mm
C _R (μF)		
0.0010		
0.0015		
0.0022		
0.0033		
0.0047		
0.0056		
0.0068		
0.010		

Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Ammo	Reel	Untaped
		$w \times h \times I$	(composition see	pack	pcs./	pcs./
mm	μF	mm	below)	pcs./MOQ	MOQ	MOQ
15	0.0010	$5.0\times10.5\times18.0$	B81123C1102M***	4680	5200	4000
	0.0015	$6.0\times11.0\times18.0$	B81123C1152M***	3840	4400	4000
	0.0022	$7.0\times12.5\times18.0$	B81123C1222M***	3320	3600	4000
	0.0033	$8.5 \times 14.5 \times 18.0$	B81123C1332M***	2720	2800	2000
	0.0047	$9.0\times17.5\times18.0$	B81123C1472M***	2560	2800	2000
22.5	0.0056	$7.0\times16.0\times26.5$	B81123C1562M***	2320	2400	2520
	0.0068	$8.5 \times 16.5 \times 26.5$	B81123C1682M***	1920	2000	2040
	0.010	$10.5\times18.5\times26.5$	B81123C1103M***	1560	1600	2160

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Composition of ordering code

+ = Capacitance tolerance code: $M = \pm 20\%$ *** = Packaging code:

- 289 = Straight terminals, Ammo pack
- 189 = Straight terminals, Reel
- 003 = Straight terminals, untaped (lead length 3.2 \pm 0.3 mm)
- 000 = Straight terminals, untaped (lead length 6 1 mm)



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Technical data

Reference standard: IEC / UL 60384-14. All data given at T = 20 °C unless otherwise specified.

Max. operating temperature T _{op,max}	+110 °C		
Dissipation factor tan δ (in 10 ⁻³)	at 1 kHz	1.0	
at 20 °C (upper limit values)	100 kHz	5.0	
Insulation resistance R _{ins}	$30\ 000\ M\Omega$		
or time constant $\tau = C_R \cdot R_{ins}$			
at 20 °C, rel. humidity \leq 65%			
(minimum as-delivered values)			
DC test voltage	4800 V, 2 s		
The repetition of this DC voltage test r	nay damage t	he capacitor. Specia	al care must be taken in
case of use several capacitors in a pa	rallel configur	ation.	
Passive flammability category	В		
Maximum continuous AC voltage V_{AC}	750 V (50/60 Hz)		
Rated AC voltage (UL60384)	500 V (50/60) Hz)	
Maximum continuous DC voltage V_{DC}	3000 V		
	$T_{op} \le 110 \ ^{\circ}C$	$V_{op} = V_{AC}$	(continuously)
temperature	$T_{op} \le 110 \ ^{\circ}C$	$V_{op} = 1.25 \cdot V_{AC}$	(1000 h)
Damp heat test	56 days / 40	°C / 93% relative hu	imidity
Limit values after damp heat test	Capacitance	change ∆C/C	≤ 5%
	Dissipation factor change Δ tan $\delta \le 0.5 \cdot 10^{-3}$ (at 1 kHz)		
	Insulation re	sistance R _{ins}	\leq 1.0 \cdot 10 ⁻³ (at 100 kHz)
	or time cons	tant $\tau = C_R \cdot R_{ins}$	\geq 50% of minimum
			as-delivered values





Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

"k_0" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V²/ μ s.

Note:

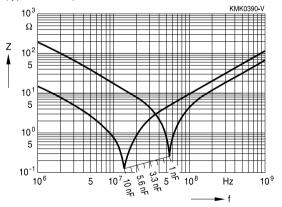
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and k₀ values

Lead spacing	15 mm	22.5 mm
dV/dt in V/µs	3 000	1 000
k₀ in V²/μs	2 100 000	700 000

Impedance Z versus frequency f

(typical values)





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Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Electrical Parameters	IEC 60384-14			Within specified limits
Robustness of terminations	IEC 60068-2-21	Tensile strength (tes Wire diameter $0.5 < d_1 \le 0.8 \text{ mm}$ $0.8 < d_1 \le 1.25 \text{ mm}$	Tensile force 10 N 20 N	Capacitance and tan δ within specified limits
Resistance to soldering heat	IEC 60068-2-20, test Tb, method 1A	Solder bath temperature at 260 ± 5 °C, immersion for 10 seconds		$\Delta C/C_0 \le 5\%$ tan δ within specified limits
Rapid change of temperature	IEC 60384-14	T_A = lower category temperature T_B = upper category temperature Five cycles, duration t = 30 min.		No visible damage $I\Delta C/C_0 I \le 5\%$ tan δ within specified limits
Vibration	IEC 60384-14	Test F_c : vibration sinusoidal Displacement: 0.75 mm Accleration: 98 m/s ² Frequency: 10 Hz 500 Hz Test duration: 3 orthogonal axes, 2 hours each axe		No visible damage
Bump	IEC 60384-14	Test Eb: Total 4000 bumps with 400 m/s ² mounted on PCB 6 ms duration		No visible damage $I\Delta C/C_0 I \le 5\%$ tan δ within specified limits
Climatic sequence	IEC 60384-14	Dry heat $- T_B / 16$ h. Damp heat cyclic, 1st cycle + 55 °C / 24h / 95% 100% RH Cold $- T_A / 2h$ Damp heat cyclic, 5 cycles + 55 °C / 24h / 95% 100% rh		No visible damage $ \Delta C/C_0 \le 5\%$ $ \Delta \tan \delta \le 0.008,$ $C \le 1 \mu F$ $ \Delta \tan \delta > 0.005,$ $C > 1 \mu F$ Voltage proof $R_{INS} \ge 50\%$ of initial limit



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Damp Heat	IEC 60384-14	Test Ca	No visible damage
Steady State		40 °C / 93% RH / 56 days	$I\Delta C/C_0 I \leq 5\%$
- · · · · · , - · · · · ·			$I\Delta \tan \delta I \leq 0.008$,
			C ≤ 1 µF
			I∆ tan δ I > 0.005,
			C > 1 μF
			Voltage proof
			$R_{INS} \ge 50\%$ of initial limit
Impulse test	IEC 60384-14	3 impulses	No visible damage
Endurance		$T_{\rm B}$ / 1.7 $V_{\rm R}$ / 1000 hours,	$I\Delta C/C_0 I \le 10\%$
		1000 V _{rms} for 0.1 s every hour	$I\Delta \tan \delta I \leq 0.008$,
			C ≤ 1 µF
			IΔ tan δ I > 0.005,
			C > 1 μF
			Voltage proof
			$R_{\text{INS}} \geq 50\%$ of initial limit
Passive	IEC 60384-14	Flame applied for a period of time	В
flammability		depending on capacitor volume	



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Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

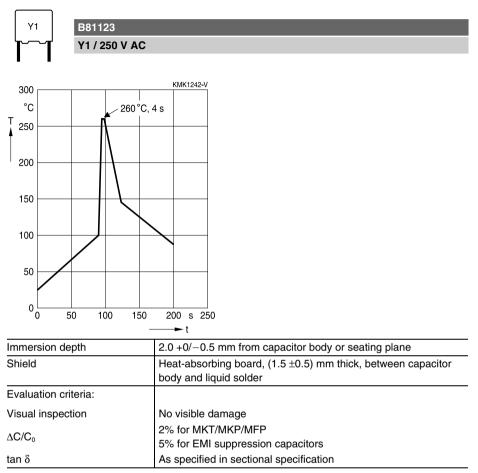
Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/ -0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder \geq 90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Serie	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5±1 s
МКР МКТ	(lead spacing \leq 7.5 mm) uncoated (lead spacing \leq 10 mm) insulated (B32559)		< 4 s recommended soldering profile for MKT uncoated (lead spacing \leq 10 mm) and insulated (B32559)







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1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
- diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings \leq 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



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Торіс	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Design of EMI Capacitors

EPCOS EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC60384-14 (3rd edition, 2005-07) / UL60384-14 (1st edition, 2009-04) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC60384-14 (3rd edition, 2005-07) / UL60384-14 (1st edition, 2009-04) establishes high voltage tests performed at 4.3 × V_R -1 minute, impulse testing at 2500 V for C= 1 µF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.





Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products**. Detailed information can be found on the Internet under <u>www.epcos.com/orderingcodes</u>.



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Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{c}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
βc	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C _R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f ₂	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F⊤	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



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Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i _z	Capacitance drift	Inkonstanz der Kapazität
k _o	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P _{diss}	Dissipated power	Abgegebene Verlustleistung
P _{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
Ri	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R _P	Parallel resistance	Parallelwiderstand
Rs	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ _₽	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ _s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the	Temperatur der Luft, die das Bauteil
• 4	component	umgibt
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{oL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
Top	Operating temperature	Beriebstemperatur
TB	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer



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Symbol	English	German
V _{AC}	AC voltage	Wechselspannung
Vc	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V _{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
Vi	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V _{op}	Operating voltage	Betriebsspannung
V _p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V _R	Rated voltage	Nennspannung
Ŷ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V _{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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